(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
3 August 2006 (03.08.2006)

PCT

(10) International Publication Number
WO 2006/081056 A3

(51) International Patent Classification:
*B23K 20/00* (2006.01) *H01L 21/607* (2006.01)
*H01L 21/60* (2006.01)

(21) International Application Number:
PCT/US2006/000540

(22) International Filing Date: 9 January 2006 (09.01.2006)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/646,950 25 January 2005 (25.01.2005) US
11/306,678 6 January 2006 (06.01.2006) US

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(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

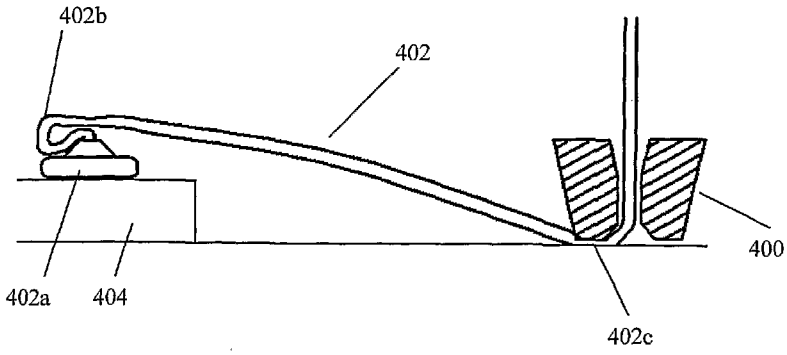
(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**Published:**
— *with international search report*
— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

(88) Date of publication of the international search report:
12 October 2006

*For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.*

(54) Title: METHOD AND APPARATUS FOR FORMING A LOW PROFILE WIRE LOOP




(57) Abstract: A method of bonding a wire between a first bonding location and a second bonding location is provided. The method includes bonding a first end of a wire to a first bonding location using a wire bonding tool to form a first wire bond. The method also includes forming a looped portion in the wire adjacent the first wire bond. The method also includes lowering the wire bonding tool in a direction towards the first wire bond after the forming step. The lowering step is interrupted prior to the wire bonding tool contacting the first wire bond. The method also includes bonding a second end of the wire to a second bonding location.

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